

The MAX9124 guad low-voltage differential signaling

(LVDS) line driver is ideal for applications requiring high

data rates, low power, and low noise. The MAX9124 is guaranteed to transmit data at speeds up to 800Mbps

(400MHz) over controlled impedance media of approxi-

mately 100 Ω . The transmission media may be printed

The MAX9124 accepts four LVTTL/LVCMOS input levels

and translates them to LVDS output signals. Moreover, the MAX9124 is capable of setting all four outputs to a high-impedance state through two enable inputs, EN and EN, thus dropping the device to an ultra-low-power state of 16mW (typ) during high impedance. The enables are

common to all four transmitters. Outputs conform to the

The MAX9124 operates from a single +3.3V supply and is specified for operation from -40°C to +85°C. It is available in 16-pin TSSOP and SO packages. Refer to the MAX9125/

MAX9126 data sheet for guad LVDS line receivers.

circuit (PC) board traces, backplanes, or cables.



Features

- Pin Compatible with DS90LV031A
- Guaranteed 800Mbps Data Rate
- 250ps Maximum Pulse Skew
- Conforms to TIA/EIA-644 LVDS Standard
- Single +3.3V Supply
- ♦ 16-Pin TSSOP and SO Packages

Ordering Information

PART	TEMP. RANGE	PIN-PACKAGE
MAX9124EUE	-40°C to +85°C	16 TSSOP
MAX9124ESE	-40°C to +85°C	16 SO

LVDS SIGNALS

*M*IXI*M*

MAX9124

Τv

LVTTL/LVCMOS

DATA INPUT

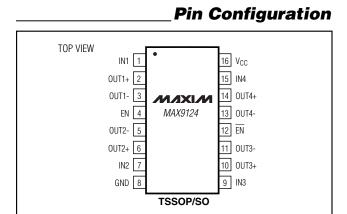
Digital Copiers
Laser Printers
Cell Phone Base Stations
Add/Drop Muxes
Digital Cross-Connects

ANSI TIA/EIA-644 LVDS standard.

Applications

DSLAMs Network Switches/Routers Backplane Interconnect Clock Distribution

General Description



* Future product—contact factory for availability.

Maxim Integrated Products 1

For pricing, delivery, and ordering information, please contact Maxim/Dallas Direct! at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

Typical Applications Circuit

15Ω

100 SHIELDED TWISTED CABLE OR MICROSTRIP PC BOARD TRACES

MIXI.M

AX9126

Rχ

Ry

Rx

LVTTL/LVCMOS

DATA OUTPUT

ABSOLUTE MAXIMUM RATINGS

V _{CC} to GND	0.3V to +4.0V
IN_, EN, EN to GND	
OUT_+, OUT to GND	0.3V to +3.9V
Short-Circuit Duration (OUT_+, OUT)	Continuous
Continuous Power Dissipation ($T_A = +7$	0°C)
16-Pin TSSOP (derate 9.4mW/°C abc	ve +70°C)755mW
16-Pin SO (derate 8.7mW/°C above -	-70°C)696mW

Storage Temperature Range	65°C to +150°C
Maximum Junction Temperature	+150°C
Operating Temperature Range	40°C to +85°C
Lead Temperature (soldering, 10s)	+300°C
ESD Protection	
Human Body Model. OUT +. OUT	±6kV

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

(V_{CC} = +3.0V to +3.6V, R_L = 100 Ω ±1%, T_A = -40°C to +85°C. Typical values are at V_{CC} = +3.3V, T_A = +25°C, unless otherwise noted.) (Notes 1, 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
LVDS OUTPUT (OUT_+, OUT)	•		•			
Differential Output Voltage	V _{OD}	Figure 1	250	368	450	mV
Change in Magnitude of V _{OD} Between Complementary Output States	ΔV _{OD}	Figure 1		1	25	mV
Offset Voltage	Vos	Figure 1	1.125	1.25	1.375	V
Change in Magnitude of V _{OS} Between Complementary Output States	ΔV _{OS}	Figure 1		4	25	mV
Output High Voltage	VOH				1.6	V
Output Low Voltage	Vol		0.90			V
Differential Output Short-Circuit Current (Note 3)	IOSD	Enabled, V _{OD} = 0			-9	mA
Output Short-Circuit Current	I _{OS}	$OUT_+ = 0$ at IN_ = V _{CC} or OUT = 0 at IN_ = 0, enabled -3.8		-3.8	-9	mA
Output High-Impedance Current	I _{OZ}	$I_{OZ} = I_{OV} \text{ and } \overline{EN} = \text{high, } OUT_+ = 0 \text{ or } V_{CC}, \\ OUT = 0 \text{ or } V_{CC}, R_L = \infty $		10	μA	
Power-Off Output Current	$V_{CC} = 0 \text{ or open, } OUT_+ = 0 \text{ or } 3.6V, OUT = 0 \text{ or } 3.6V, R_L = \infty$		-10		10	μA
INPUTS (IN_, EN, EN)	•		•			
High-Level Input Voltage	VIH		2.0		VCC	V
Low-Level Input Voltage	VIL		GND		0.8	V
Input Current	lin	IN_, EN, $\overline{EN} = 0$ or V_{CC}	-20		20	μA
SUPPLY CURRENT						
No-Load Supply Current	Icc	$R_L = \infty$, $IN = V_{CC}$ or 0 for all channels		9.2	11	mA
Loaded Supply Current	ICCL	R_L = 100Ω, IN_ = V_{CC} or 0 for all channels		22.7	30	mA
Disabled Supply Current	ICCZ	Disabled, IN_ = V _{CC} or 0 for all channels, EN = 0, \overline{EN} = V _{CC}		4.9	6	mA

SWITCHING CHARACTERISTICS

(V_{CC} = +3.0V to +3.6V, R_L = 100 Ω ±1%, C_L = 10pF, T_A = -40°C to +85°C. Typical values are at V_{CC} = +3.3V, T_A = +25°C, unless otherwise noted.) (Notes 4, 5, 6)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
Differential Propagation Delay High to Low	^t PHLD	Figures 2 and 3		1.42	2.0	ns
Differential Propagation Delay Low to High	tplhd	Figures 2 and 3		1.44	2.0	ns
Differential Pulse Skew (Note 7)	tskD1	Figures 2 and 3		0.02	0.25	ns
Differential Channel-to-Channel Skew (Note 8)	tskd2	Figures 2 and 3			0.35	ns
Differential Part-to-Part Skew (Note 9)	tskd3	Figures 2 and 3			0.8	ns
Differential Part-to-Part Skew (Note 10)	^t SKD4	Figures 2 and 3			1.2	ns
Rise Time	ttlh	Figures 2 and 3	0.1	0.35	0.7	ns
Fall Time	t _{THL}	Figures 2 and 3 0.1		0.35	0.7	ns
Disable Time High to Z	t _{PHZ}	Figures 4 and 5			5	ns
Disable Time Low to Z	t _{PLZ}	Figures 4 and 5			5	ns
Enable Time Z to High	t _{PZH}	Figures 4 and 5			5	ns
Enable Time Z to Low	tpzl	Figures 4 and 5			5	ns
Maximum Operating Frequency (Note 11)	fMAX		400			MHz

Note 1: Maximum and minimum limits over temperature are guaranteed by design and characterization. Devices are 100% tested at $T_A = +25^{\circ}C$.

Note 2: Currents into the device are positive, and current out of the device is negative. All voltages are referenced to ground except VOD.

Note 3: Guaranteed by correlation data.

Note 4: AC parameters are guaranteed by design and characterization.

- **Note 5:** C_L includes probe and jig capacitance.
- Note 6: Signal generator conditions for dynamic tests: $V_{OL} = 0$, $V_{OH} = 3V$, f = 100MHz, 50% duty cycle, $R_O = 50\Omega$, $t_R \le 1$ ns, $t_F \le 1$ ns (0% to 100%).

Note 7: t_{SKD1} is the magnitude difference of differential propagation delay. $t_{SKD1} = lt_{PHLD} - t_{PLHD}l$.

Note 8: t_{SKD2} is the magnitude difference of t_{PHLD} or t_{PLHD} of one channel to the t_{PHLD} or t_{PLHD} of another channel on the same device.

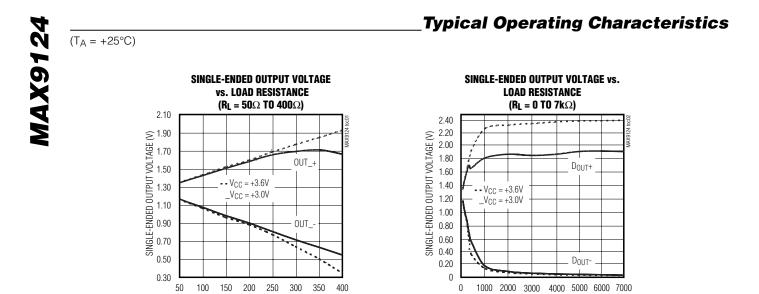
Note 9: t_{SKD3} is the magnitude difference of any differential propagation delays between devices at the same V_{CC} and within 5°C of each other.

Note 10: t_{SKD4} is the magnitude difference of any differential propagation delays between devices operating over the rated supply and temperature ranges.

Note 11: f_{MAX} signal generator conditions: $V_{OL} = 0$, $V_{OH} = 3V$, f = 400MHz, 50% duty cycle, $R_O = 50\Omega$, $t_R \le 1$ ns, $t_F \le 1$ ns (0% to 100%). Transmitter output criteria: duty cycle = 45% to 55%, $V_{OD} \ge 250$ mV.

M/IXI/M

 $\mathsf{R}_{\mathsf{L}}(\Omega)$



Pin Description

 $\mathsf{R}_{\mathsf{L}}\left(\Omega\right)$

PIN	NAME	FUNCTION
1, 7, 9, 15	IN_	LVTTL/LVCMOS Driver Inputs
2, 6, 10, 14	OUT_+	Noninverting LVDS Driver Outputs
3, 5, 11, 13	OUT	Inverting LVDS Driver Outputs
4, 12	EN, ĒN	Driver Enable Inputs. The driver is disabled and in high impedance when EN is low and \overline{EN} is high. For other combinations of EN and \overline{EN} , the outputs are active.
8	GND	Ground
16	V _{CC}	Power-Supply Input. Bypass V _{CC} to GND with 0.1 μ F and 0.001 μ F ceramic capacitors.

Detailed Description

The LVDS interface standard is a signaling method intended for point-to-point communication over a controlled-impedance medium as defined by the ANSI/TIA/EIA-644 and IEEE 1596.3 standards. The LVDS standard uses a lower voltage swing than other common communication standards, achieving higher data rates with reduced power consumption while reducing EMI emissions and system susceptibility to noise.

The MAX9124 is an 800Mbps quad differential LVDS driver that is designed for high-speed, point-to-point, and low-power applications. This device accepts LVTTL/LVCMOS input levels and translates them to LVDS output signals.

The MAX9124 generates a 2.5mA to 4.0mA output current using a current-steering configuration. This currentsteering approach induces less ground bounce and no shoot-through current, enhancing noise margin and system speed performance. The driver outputs are shortcircuit current limited and enter a high-impedance state when the device is not powered or is disabled.

The current-steering architecture of the MAX9124 requires a resistive load to terminate the signal and complete the transmission loop. Because the device switches current and not voltage, the actual output voltage swing is determined by the value of the termination resistor at the input of an LVDS receiver. Logic states are determined by the direction of current flow through the termination resistor. With a typical 3.7mA output current, the MAX9124 produces an output voltage of 370mV when driving a 100 Ω load.

Termination Because the MAX9124 is a current-steering device, no output voltage will be generated without a termination resistor. The termination resistors should match the differential impedance of the transmission line. Output voltage levels depend upon the value of the termination resistor. The MAX9124 is optimized for point-to-point interface with 100 Ω termination resistors at the receiver inputs. Termination resistance values may range between 90 Ω and 132 Ω , depending on the characteristic impedance of the transmission medium.

Applications Information

Power-Supply Bypassing

Bypass V_{CC} with high-frequency, surface-mount ceramic 0.1μ F and 0.001μ F capacitors in parallel as

Table 1. Input/Output Function Table

ENABLES		INPUTS	OUTPUTS		
EN	ĒN	IN_	OUT_+	OUT	
L	Н	Х	Z	Z	
All other combinations		L	L	Н	
of ENAB	LE inputs	Н	Н	L	

close to the device as possible, with the smaller valued capacitor closest to $V_{\mbox{CC}}.$

Differential Traces

Output trace characteristics affect the performance of the MAX9124. Use controlled-impedance traces to match trace impedance to the transmission medium. Eliminate reflections and ensure that noise couples as common mode by running the differential trace pairs close together. Reduce skew by matching the electrical length of the traces. Excessive skew can result in a degradation of magnetic field cancellation.

Maintain the distance between the differential traces to avoid discontinuities in differential impedance. Avoid 90° turns and minimize the number of vias to further prevent impedance discontinuities.

Cables and Connectors

Transmission media should have a nominal differential impedance of 100Ω . To minimize impedance discontinuities, use cables and connectors that have matched differential impedance.

Avoid the use of unbalanced cables such as ribbon or simple coaxial cable. Balanced cables, such as twisted pair, offer superior signal quality and tend to generate less EMI due to canceling effects. Balanced cables tend to pick up noise as common mode, which is rejected by the LVDS receiver.

Board Layout

For LVDS applications, a four-layer PC board that provides separate power, ground, LVDS signals, and input signals is recommended. Isolate the LVTTL/LVCMOS and LVDS signals from each other to prevent coupling.

Chip Information

TRANSISTOR COUNT: 2007 PROCESS: CMOS



MAX9124

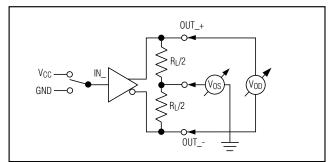


Figure 1. Driver VOD and VOS Test Circuit

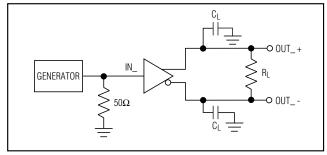


Figure 2. Driver Propagation Delay and Transition Time Test Circuit

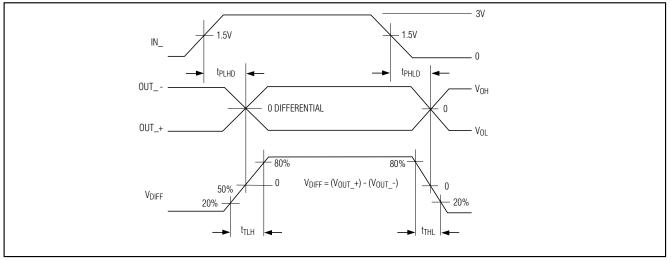


Figure 3. Driver Propagation Delay and Transition Time Waveforms

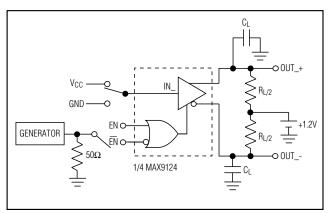


Figure 4. Driver High-Impedance Delay Test Circuit

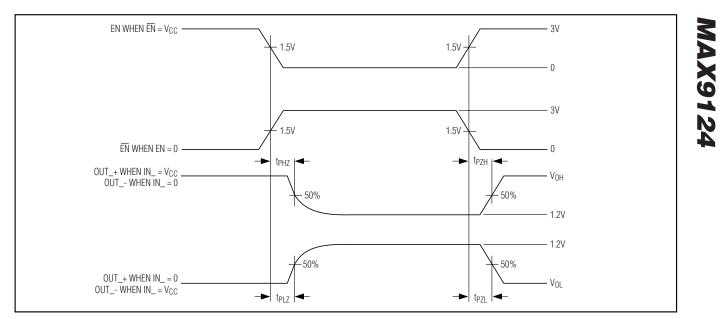
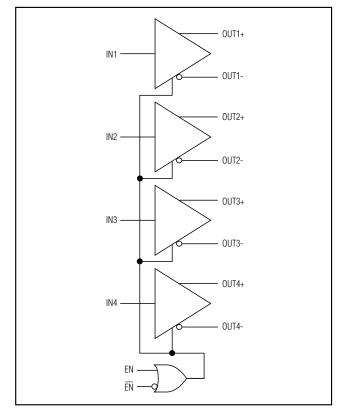
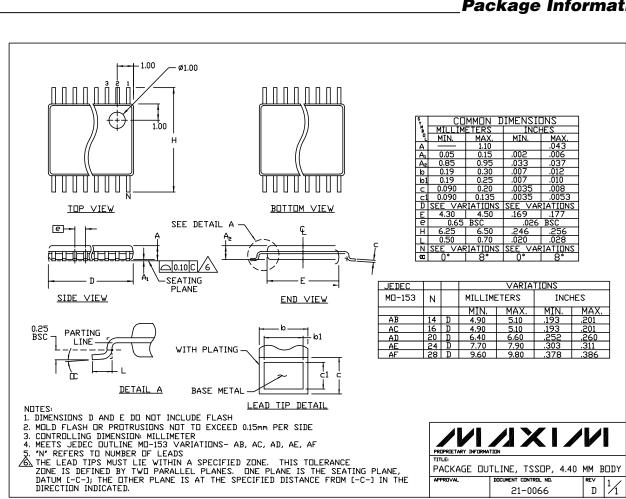


Figure 5. Driver High-Impedance Delay Waveform



Functional Diagram

7



Package Information

TSSOP,NO PADS.EPS

MAX9124

П ΕН 1 ΗĦ 日日 F 0°-8° र्ग्तन्त कि А INCHES MILLIMETERS INCHES MILLIMETERS INCHES MILLIMETERS MIN MAX MIN MAX A 0.053 0.069 1.35 1.75 A1 0.004 0.010 0.10 0.25 B 0.014 0.019 0.35 0.49 C 0.007 0.010 0.19 0.25 MIN MAX MIN MAX M MS012 D 0.189 0.197 4.80 5.00 8 A D 0.337 0.344 8.55 8.75 14 B D 0.386 0.394 9.80 10.00 16 C NUTES: 1. D&E DD NOT INCLUDE MOLD FLASH 2. MOLD FLASH DR PROTRUSIONS NOT TO EXCEED .15mm (006') 3. LEADS TO BE COPLANAR WITHIN .102mm (004') 4. CONTROLLING DIMENSION: MILLIMETER 5. MEETS JEDEC MS012-XX AS SHOWN IN ABOVE TABLE 6. N = NUMBER OF PINS 0.050 е 1.27 E 0.150 0.157 3.80 4.00 H 0.228 0.244 5.80 6.20 h 0.010 0.020 0.25 0.50 L 0.016 0.050 0.40 1.27 PACKAGE FAMILY DUTLINE: SDIC .150" 1 21-0041 A

Package Information (continued)

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

Maxim Integrated Products, 120 San Gabriel Drive, Sunnyvale, CA 94086 408-737-7600 _

© 2001 Maxim Integrated Products Printed USA MAXIM is a registered trademark of Maxim Integrated Products.